

MacDermid Alpha Launches ALPHA CVP-390V High Reliability Solder Paste for Harsh Operating Conditions

(Waterbury, CT USA) – April 15th, 2021 - MacDermid Alpha Electronics Solutions, a global leader in specialty materials for electronics, announces the release of ALPHA CVP-390V high reliability solder paste, designed to maximize flexibility in manufacturing and provide excellent electrochemical reliability in harsh operating conditions.

ALPHA CVP-390V is a next generation broad latitude chemistry that delivers consistent print and reflow performance across a wide range of component types and feature sizes. ALPHA CVP-390V exhibits best-in-class electrochemical reliability down to 0.100mm comb spacing against the most challenging automotive SIR profiles. The compatibility with the Innot alloy and ability to maintain high electrochemical performance in harsh operating conditions on dense assembly designs makes ALPHA CVP-390V ideal for high reliability applications.

“ALPHA CVP-390V represents the continual evolution of our industry leading solder paste portfolio to ensure superior performance and reliability on complex PCB assemblies, comments Paul Salerno, Global Portfolio Manager, SMT at MacDermid Alpha. “Assemblies requiring flexibility across multiple component types and assemblies requiring fine feature printability and increased manufacturing throughput can also benefit from ALPHA CVP-390V.”

For more information on ALPHA CVP-390V solder paste please visit [MacDermidAlpha.com](https://www.MacDermidAlpha.com).

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